

REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2011.03.11	Ivy
A1	Release To ECN20130208	2013.02.27	Seven
A2	Release To ECN20150206	2015.02.11	Michelle

**RoHS Compliant**

**Specification**

- 1.Current Rating:1A AC/DC
- 2.Voltage Rating:600V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min.
- 5.Dielectric Withstanding Voltage:AC1800V/Minute
- 6.Operating Temperature:-25°C~+85°C

**Material:**

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.30mm
- 3.Contact Pin:Copper Alloy T=0.50mm

**Finish:**

- 1.Housing:Natural
- 2.Tab:Matte Tin Plated Over Nickel
- 3.Contact Pin:Matte Tin Plated Over Nickel

**Part No.:** AS01736 04 5 2 X 1

No. Of Pin: 04

Packing: 1:T&R, 4:Tube

Housing Material: 5:HTN UL94V-0 Natural

Plating: 2:Matte Tin Plated Over Nickel

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104. 2. 11  
文管中心

**金上達科技股份有限公司**  
GOLDENSUNDA TECHNOLOGY CO.,LTD

**TOLERANCE UNLESS OTHERWISE SPECIFIED**

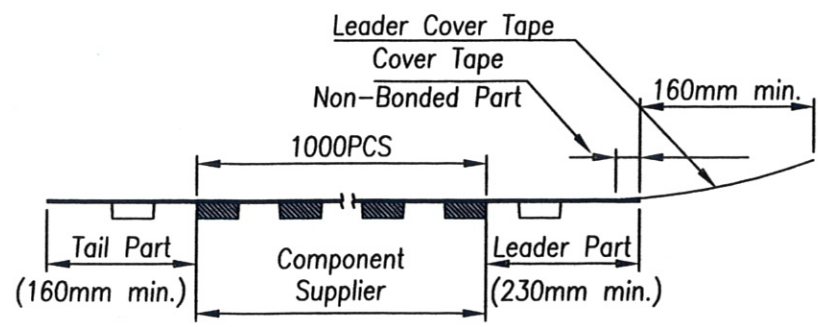
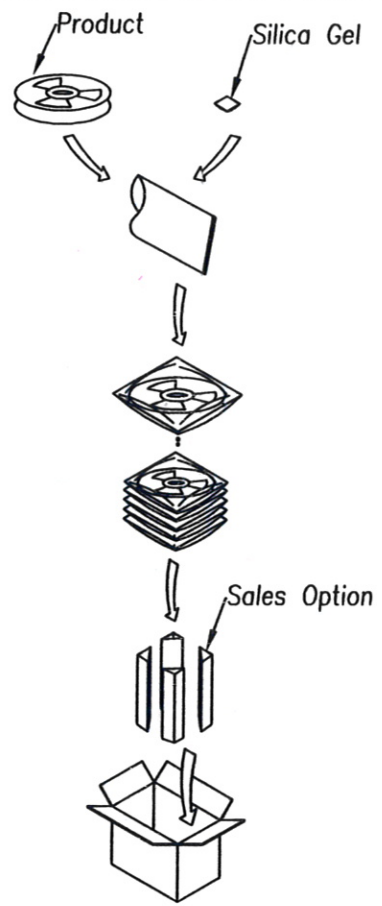
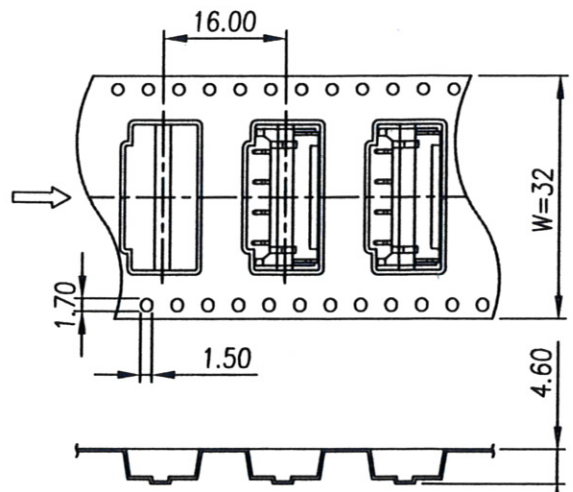
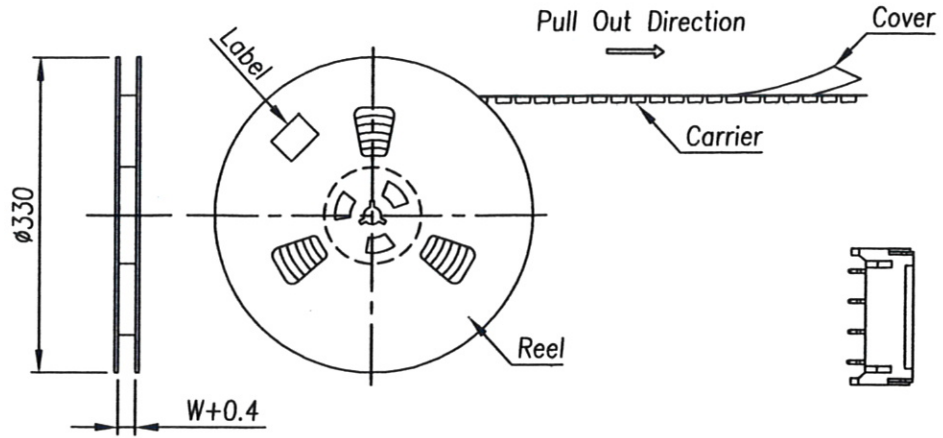
.x± 0.35	x.'± 2'	APR. C.F.Liao 20150211	TITLE: Wire To Board Wafer 4.00mm 90° SMT (7Holes 4Pin) Single Row
.xx± 0.25	.x'± 1'	CHK. Abel 20150211	PART NO. AS017360452X1 DWG NO. AS017360452X1
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150211	UNITS: mm CUSTOMER DRAWING

SIZE: A4    SCALE 5:1    SHEET 1 / 2    REV A2

RoHS Compliant

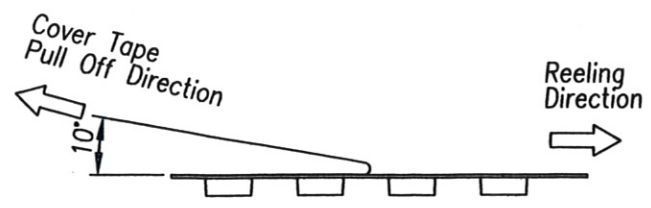



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Notes:  
1. Material PS

P/N NO.	W±0.30	PCS / REEL
AS01736045211	32	1000





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.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150211	UNITS: mm	SIZE: <b>A4</b>
		SCALE Free	SHEET 2 / 2	REV A2